

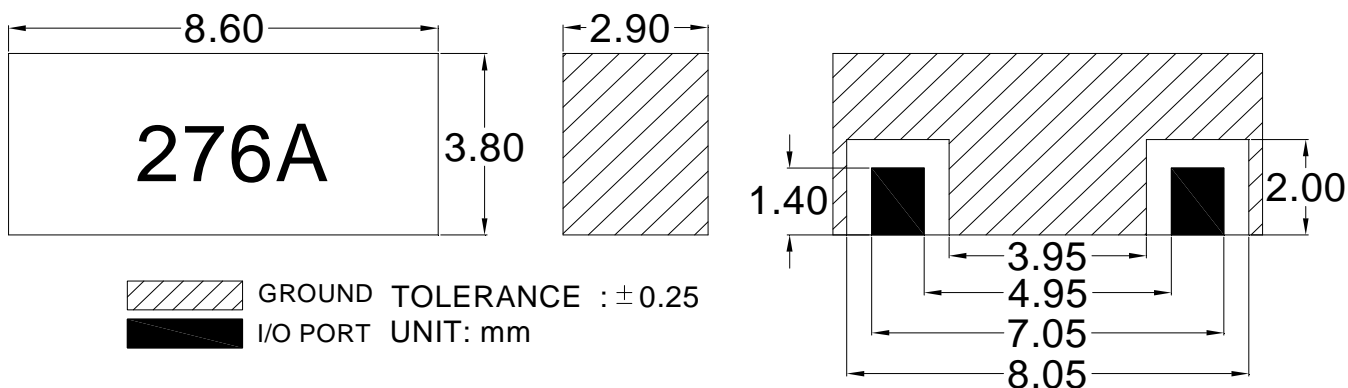
FEATURES

- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

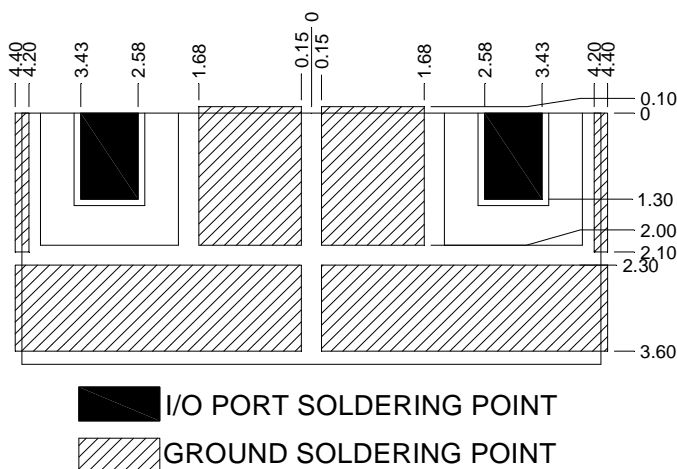
SPECIFICATIONS

NO.	ITEM	SPEC	UNIT
1	Center Frequency [fo]	5235.0	MHz
2	Bandwidth [BW]	fo ± 90	MHz
3	Insertion Loss in BW	2.5 max	dB
4	Ripple in BW	1.3 max	dB
5	Return Loss in BW	10.0 min	dB
6	Attenuations	50.0 min @ 5490 ~ 5850 MHz	dB

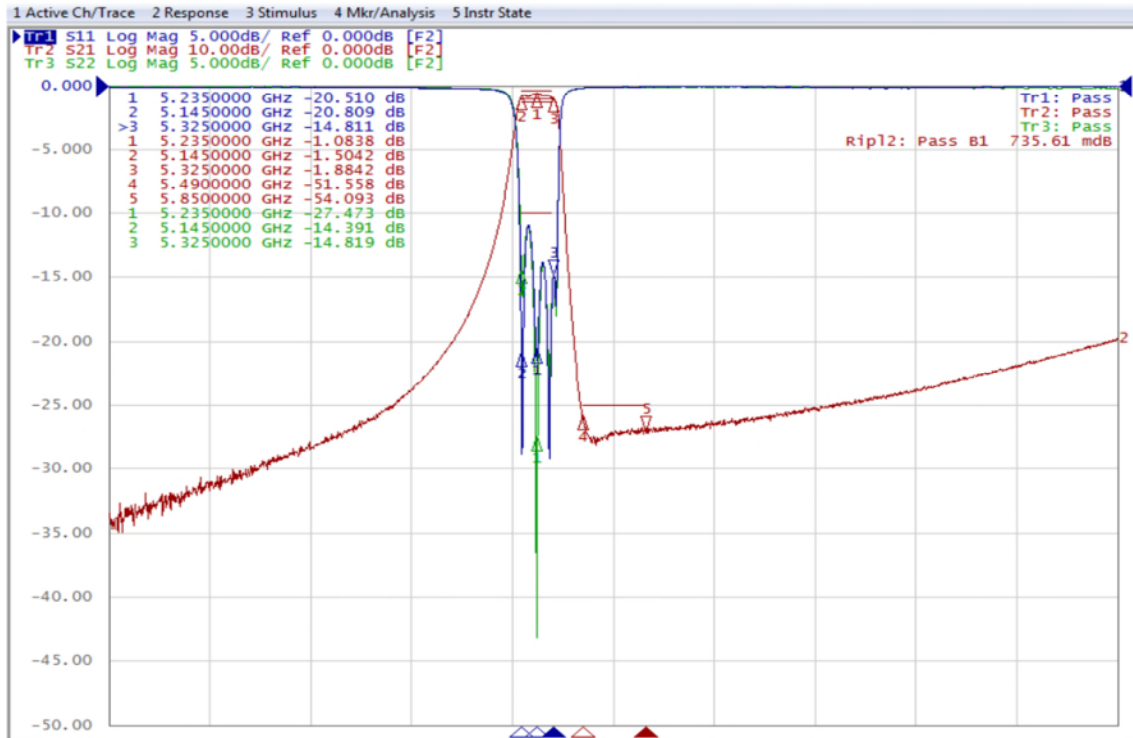
OUTLINE DRAWING



FOOTPRINT



ELECTRICAL CHARACTERISTICS CURVE



ABSOLUTE MAXIMUM RATINGS

Operation Temperature	-40°C to +85°C
Storage Temperature	-40°C to +85°C
Input Power	1 w max

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curve

